

Application Information

Application Type::	Regular
Subject Matter::	Utility
Suggested Group Art Unit::	N/A
CD-ROM or CD-R?::	None
Sequence submission?::	None
Computer Readable Form (CRF)?::	No
Title::	SILICON SUBSTRATE ETCHING METHOD AND ETCHING APPARATUS
Attorney Docket Number::	20110/0200839-US0
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	1
Total Drawing Sheets::	5
Small Entity?::	No
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
Given Name::	Kazuo
Family Name::	Kasai
City of Residence::	Amagasaki-shi
Country of Residence::	Japan
Street of mailing address::	c/o Sumitomo Precision Products Co., Ltd. 1-10, Fuso-cho
City of mailing address::	Amagasaki-shi, Hyogo
Country of mailing address::	Japan

Representative Customer Number:: 07278

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
This Application	Continuation of	PCT/JP02/09734	09/20/02

Foreign Priority Information

Country::	Application number::	FilingDate::	Priority Claimed::
Japan	2001-299435	09/28/01	Yes

Assignee Information

Assignee name:: Sumitomo Precision Products Co., Ltd.
Street of mailing address:: 1-10, Fuso-cho
City of mailing address:: Amagasaki-shi, Hyogo
Country of mailing address:: Japan
Postal or Zip Code of mailing address:: 660-0891